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**CERTIFICATE OF MAILING** 

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Kristi L. Davidson, Reg. No. 44.643

6/15/05

Date

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

10/797,425

Filed:

March 10, 2004

Group Art Unit:

2811

Examiner:

Shouxiang Hu

Applicant:

Pradip K. Roy, Anthony Dip, Allen J. Leith, Seungho Oh

Title:

SILICON-GERMANIUM THIN LAYER SEMICONDUCTOR

STRUCTURE WITH VARIABLE SILICON-GERMANIUM

COMPOSITION AND METHOD OF FABRICATION

Attorney Docket: Confirmation No.:

TPS-008 4397

Cincinnati, Ohio 45202

June 15, 2005

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

In accordance with the duty of candor and good faith imposed by 37 C.F.R. §1.56, and means of complying therewith according to 37 C.F.R. §\$1.97 and 1.98, the references listed on the attached Form PTO-1449 are called to the attention of the United States Patent and Trademark Office in connection with the above-identified patent application. Because the requirement (37 C.F.R. §1.98(a)(2)(i)) for submitting copies of U.S. patents and published applications has been

waived, copies of only the foreign cited references and/or other documents are enclosed herewith.

Applicants have also enclosed a copy of the foreign Search Report listing these references.

It is submitted that the cited references do not disclose or render obvious the subject

matter claimed in the present application.

Certifications under 37 C.F.R. § 1.97(e) and § 1.704(d)

Each item of information contained in the information disclosure statement was first

cited in a communication from a foreign patent office in a counterpart foreign application not more

than three months prior to the filing of the information disclosure statement.

Each item of information contained in the information disclosure statement was

cited in a communication from a foreign patent office in a counterpart application and to the

knowledge of the person signing the certification after making reasonable inquiry, no item of

information contained in the information disclosure statement was known to any individual

designated in 37 C.F.R. § 1.56(c) more than thirty days prior to the filing of the information

disclosure statement.

Applicants do not believe that any fees are due in connection with this submission.

However, if such petition is due or any fees are necessary, the Commissioner may consider this to

be a request for such and charge any necessary fees to Deposit Account No. 23-3000.

Respectfully submitted,

WOOD, HERRON & EVANS, L.L.P.

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SUBSTITUTE FORM 2TO-1449 (MODIFUED)											COMMERCE IARK OFFICE	ATTY. DOCKET NO. TPS-008			SERIAL NO. 10/797,425	
l NUL	INFORMATION DISCLOSURE STATEMENT BY APPLICANT											APPLICANT Pradip K. Roy et al.				
(37 CR 1,98(b)) (Use several sheets if necessary)											FILING DATE March 10, 2004			GROUP 2811		
	RADES								U.S. F	PATENT	DOCUMENTS				-	
EXAMINER INITIAL			PATENT NUMBER						ISSUE DATE	PATENTEE		CLASS		SUBCLASS		FILING DATE IF APPROPRIATE
	A.A	6	4	2	3	6	3	2	07/23/2002	Samav	redam et al.		438	652		07/21/2000
	A.B															
	A.C															
	A.D															
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FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS																
		DOCUMENT NUMBER						PUBLICATION DATE			COUNTRY OR PATENT OFFICE		CLASS	SUBCLASS		TRANSLATION (YES/NO)
	A.L															
	A.M															
	A.N															
	A.O															
	A.P								1							
	A.Q															
	OTHER DOCUMENTS (Including Author, Title, Date, Place of Publication)															
•	A.R	Luo pub	Luo et al., Seedless Method of Forming a Silicon Germanium Layer on a Gate Dielectric Layer, US 2004/0009680 A1; publication date 01/15/2004; filed 07/10/2002; U.S. Class 438/933													
	A.S		Uejima et al., <u>Highly Reliable Poly-SiGe/Amorphous-Si Gate CMOS</u> , Electron Devices Meeting; IEDM Technical Digest; pp. 445-448; 12/10/2000													
	A.T	v.T														
EXAMINER								DATE CONSIDERED								
EXAMINER: In Include a copy	itial if cit	ation	cor	nsid nex	erec t co	l, wh	eth	er or	not in conform to Applicant.	nance. [	Draw line throug	h citation	only if not in	n conform	ance <u>an</u>	d not considered.